

Plastic-Encapsulate Diodes

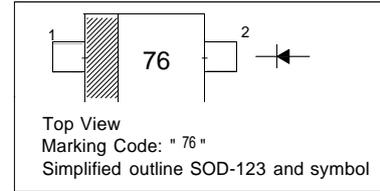
Schottky Barrier Diode

FEATURES

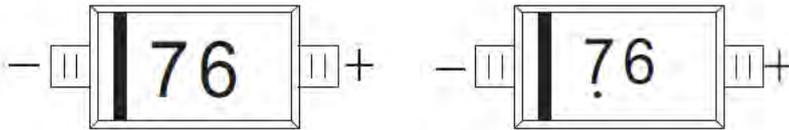
- Small Power Mold Type
- Low I_R
- High Reliability

PINNING

PIN	DESCRIPTION
1	Cathode
2	Anode



MARKING: 76



The marking bar indicates the cathode
Solid dot = Green molding compound device, if none, the normal device.

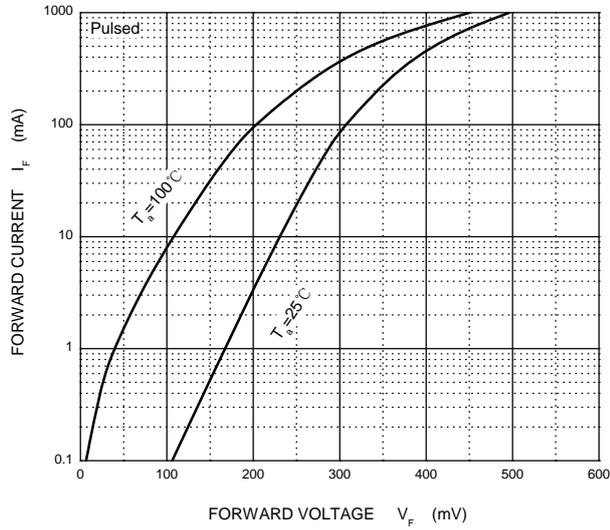
Maximum Ratings @ $T_a=25^\circ\text{C}$

Parameter	Symbol	Limit	Unit
DC reverse voltage	V_R	60	V
Mean rectifying current	I_o	1	A
Peak forward surge current 4 H ₁ , " a g	I_{FSM}	F ₁	A
Power dissipation	D_8	350	mW
Thermal Resistance Junction to Ambient	θ_{j-a}	286	$^\circ\text{C}/\text{W}$
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55~+150	$^\circ\text{C}$

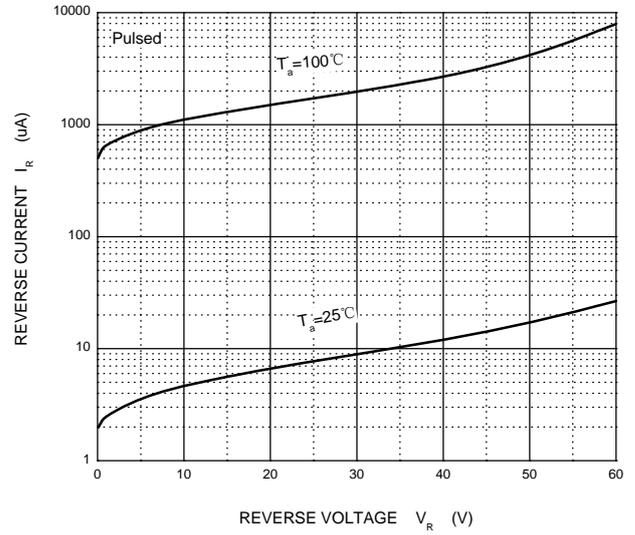
Electrical characteristics @ $T_a=25^\circ\text{C}$

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_F			0.58	V	$I_F=1\text{A}$
Reverse current	I_R			30	μA	$V_R=60\text{V}$

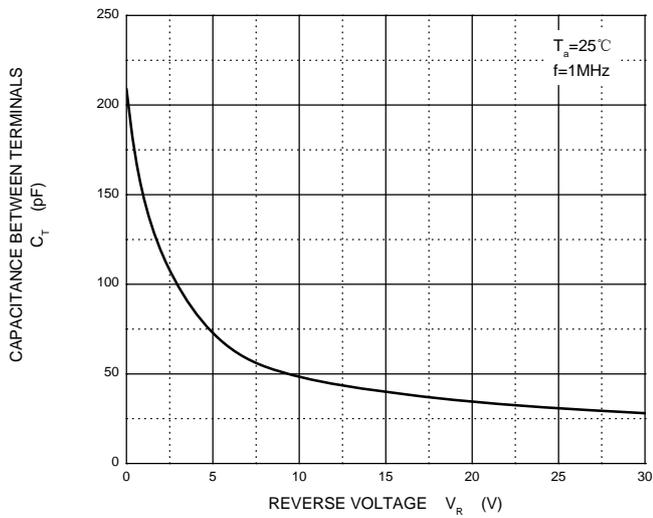
Forward Characteristics



Reverse Characteristics



Capacitance Characteristics



Power Derating Curve

